

IN THE CLAIMS:

In accordance with 37 CFR § 1.121, please substitute for original claims 1 and 12, the following rewritten versions of the same claims, as amended. The changes are shown explicitly in the attached "Marked Up Version Showing Changes Made."

Please amend the following claims 1 and 12.

1. (Amended) A semiconductor device wiring board wherein an opening is defined at a predetermined position of a film-like insulating substrate, an electric wiring provided with a connection terminal covering the opening is disposed on a principal plane of the insulating substrate, and a conductive member connected with the connection terminal of the electric wiring is disposed inside the opening, comprising:

said conductive member having a thickness from a surface on which said electric wiring of the insulating substrate has been disposed being thinner than that of said insulating substrate so as to prevent said conductive member from projecting from the surface opposite to the surface on which said electric wiring is formed, and said conductive member and a soldering paste applied on an electric wiring of a mount board are connected by soaking up part of said soldering paste into said opening.

12. (Amended) A semiconductor device wherein a wiring board in which an opening is defined at a predetermined position of a film-like insulating substrate, an electric wiring provided with a connection terminal covering said opening is disposed on a principal plane of said insulating substrate, and a conductive member connected with the connection terminal of said electric wiring is disposed inside the opening is placed; a semiconductor chip is placed on the surface of said wiring board on which said electric wiring has been disposed; the electric wiring of said wiring board is electrically connected with an external electrode of the semiconductor chip; and said semiconductor chip, said electric wiring, and a connecting section for said electric wiring and said

external electrode of the semiconductor chip are sealed with a sealing insulator, comprising:

said conductive member having a thickness from a surface on which said electric wiring of the insulating substrate has been formed being thinner than that of said insulating substrate so as to prevent said conductive member from projecting from the surface opposite to the surface on which said electric wiring is formed, and said conductive member and a soldering paste applied on an electric wiring of a mount board are connected by soaking up part of said soldering paste into said opening.